

APTD3216LZGCK

3.2 x 1.6 mm SMD Chip LED Lamp



DESCRIPTIONS

- The Green source color devices are made with InGaN on Sapphire Light Emitting Diode
- · Electrostatic discharge and power surge could damage the LEDs
- · It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs
- · All devices, equipments and machineries must be electrically grounded

FEATURES

- 3.2 mm x 1.6 mm SMD LED, 1.8 mm thickness
- Low power consumption
- · Ideal for backlight and indicator
- Package: 2000 pcs / reel
- Moisture sensitivity level: 3
- RoHS compliant

APPLICATIONS

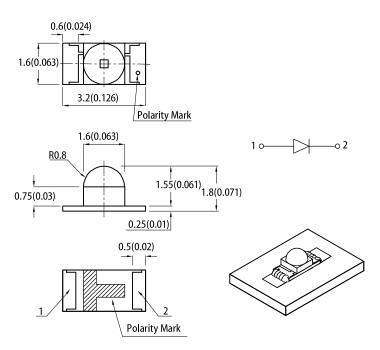
- Backlight
- Status indicator
- · Home and smart appliances
- · Wearable and portable devices
- · Healthcare applications

ATTENTION

Observe precautions for handling electrostatic discharge sensitive devices

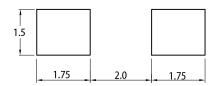


PACKAGE DIMENSIONS



RECOMMENDED SOLDERING PATTERN

(units : mm; tolerance : ± 0.1)



Notes

All dimensions are in millimeters (inches).
Tolerance is ±0.2(0.008") unless otherwise noted.
The specifications, characteristics and technical data described in the datasheet are subject to

change without prior notice. 4. The device has a single mounting surface. The device must be mounted according to the specifications.

SELECTION GUIDE

Part Number	Emitting Color (Material)	Lens Type	lv (mcd) @ 2mA ^[2]		Viewing Angle ^[1]
			Min.	Тур.	201/2
APTD3216LZGCK	Green (InGaN)	Water Clear	180	290	30°

Notes

41/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
2. Luminous intensity / luminous flux: +/-15%.
3. Luminous intensity value is traceable to CIE127-2007 standards.

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ELECTRICAL / OPTICAL CHARACTERISTICS at T_A=25°C

Parameter	Symbol	Emitting Color	Value			11-24
Parameter			Min.	Тур.	Max.	Unit
Wavelength at Peak Emission I_F = 2mA	λ_{peak}	Green	-	515	-	nm
Dominant Wavelength I _F = 2mA	λ_{dom} ^[1]	Green	-	525	-	nm
Spectral Bandwidth at 50% Φ REL MAX I _F = 2mA	Δλ	Green	-	35	-	nm
Capacitance	С	Green	-	45	-	pF
Forward Voltage I _F = 2mA	V _F ^[2]	Green	2.2	2.65	3.1	V
Reverse Current ($V_R = 5V$)	I _R	Green	-	-	50	uA
Temperature Coefficient of λ_{peak} I_F = 20mA, -10°C $\leq T \leq 85^\circ C$	TC_{\lambdapeak}	Green	-	0.05	-	nm/°C
Temperature Coefficient of λ_{dom} I_F = 20mA, -10°C $\leq T \leq 85°C$	$TC_{\lambda dom}$	Green	-	0.03	-	nm/°C
Temperature Coefficient of V_F I_F = 20mA, -10°C \leq T \leq 85°C	TCv	Green	-	-3.0	-	mV/°C

Notes:

The dominant wavelength (λd) above is the setup value of the sorting machine. (Tolerance λd : ±1nm.)
Forward voltage: ±0.1V.
Wavelength value is traceable to CIE127-2007 standards.
Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

ABSOLUTE MAXIMUM RATINGS at $T_A=25^{\circ}C$

Parameter	Symbol	Value	Unit
Power Dissipation	P _D	102.5	mW
Reverse Voltage	V _R	5	V
Junction Temperature	Tj	115	°C
Operating Temperature	T _{op}	-40 to +85	°C
Storage Temperature	T _{stg}	-40 to +85	°C
DC Forward Current	I _F	25	mA
Peak Forward Current	I _{FM} ^[1]	150	mA
Electrostatic Discharge Threshold (HBM)	-	450	V
Thermal Resistance (Junction / Ambient)	R _{th JA} ^[2]	530	°C/W
Thermal Resistance (Junction / Solder point)	R _{th JS} ^[2]	420	°C/W

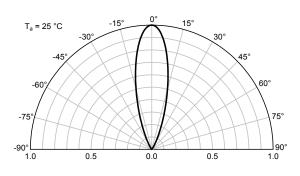
Notes: 1. /1/10 Duty Cycle, 0.1ms Pulse Width. 2. R_{in, Ja}, R_{in, JS} Results from mounting on PC board FR4 (pad size ≥ 16 mm² per pad). 3. Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/J-STD-033.

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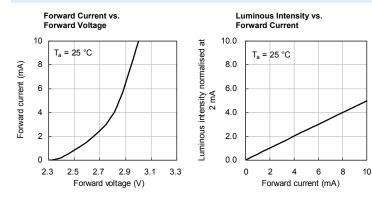
TECHNICAL DATA

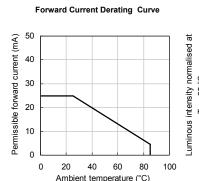
RELATIVE INTENSITY vs. WAVELENGTH Greer 100% T_a = 25 °C Relative Intensity (a. u.) 80% 60% 40% 20% 0% 800 350 400 450 500 550 600 650 700 750 Wavelength (nm)

SPATIAL DISTRIBUTION

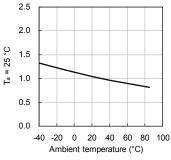


GREEN

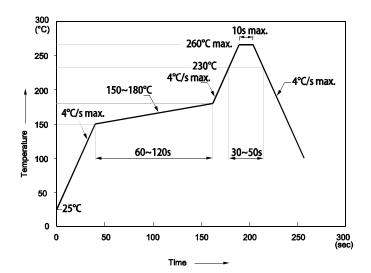




Luminous Intensity vs. Ambient Temperature



REFLOW SOLDERING PROFILE for LEAD-FREE SMD PROCESS



Notes:

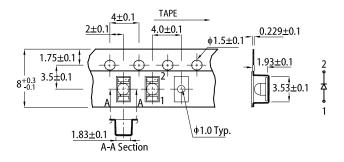
1. We recommend the reflow temperature 245°C(+/- 5°C). The maximum soldering temperature should be limited to 260°C.

Don't cause stress to the epoxy resin while it is exposed to high temperature.

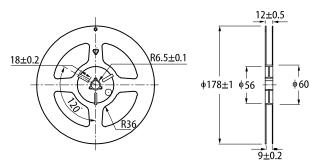
3. 4.

Number of reflow process shall be 2 times or less. Reflow soldering is recommended .Other soldering methods are not recommended as they might cause damage to the product.

TAPE SPECIFICATIONS (units : mm)

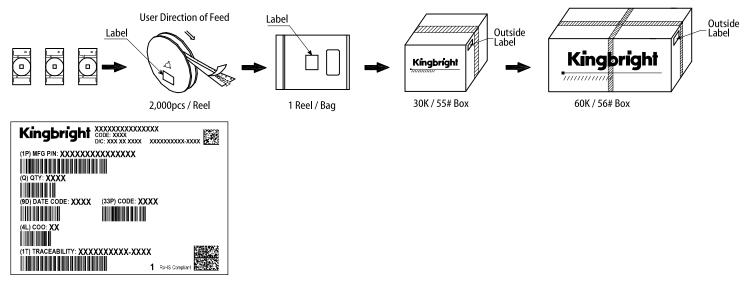


REEL DIMENSION (units : mm)



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PACKING & LABEL SPECIFICATIONS



PRECAUTIONARY NOTES

- 1. 2.
- The information included in this document reflects representative usage scenarios and is intended for technical reference only. The part number, type, and specifications mentioned in this document are subject to future change and improvement without notice. Before production usage customer should refer to the latest datasheet for the updated specifications.
- 3. When using the products referenced in this document, please make sure the product is being operated within the environmental and electrical limits specified in the datasheet. If customer usage exceeds the specified limits. Kingbright will not be responsible for any subsequent issues. The information in this document applies to typical usage in consumer electronics applications. If customer's application has special reliability requirements or have life-threatening
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